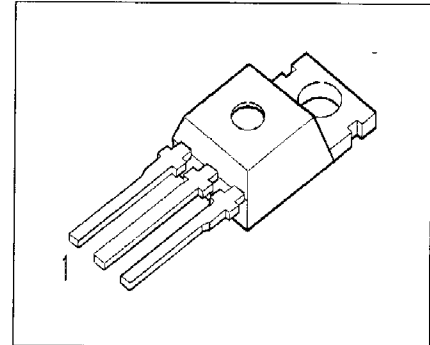


**BUZ 50 A**

- N channel
- Enhancement mode

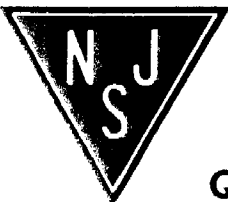


<b>Pin 1</b>	<b>Pin 2</b>	<b>Pin 3</b>
G	D	S

Type	$V_{DS}$	$I_D$	$R_{DS(on)}$	Package
BUZ 50 A	1000 V	2.5 A	5 $\Omega$	TO-220 AB

**Maximum Ratings**

Parameter	Symbol	Values	Unit
Drain source voltage	$V_{DS}$	1000	V
Drain-gate voltage $R_{GS} = 20 \text{ k}\Omega$	$V_{DGR}$	1000	
Continuous drain current $T_C = 25 \text{ }^\circ\text{C}$	$I_D$	2.5	A
Pulsed drain current $T_C = 25 \text{ }^\circ\text{C}$	$I_{Dpuls}$	10	
Gate source voltage	$V_{GS}$	$\pm 20$	V
Power dissipation $T_C = 25 \text{ }^\circ\text{C}$	$P_{tot}$	75	W
Operating temperature	$T_j$	-55 ... ... + 150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 ... ... + 150	
Thermal resistance, chip case	$R_{thJC}$	$\leq 1.6$	K/W
Thermal resistance, chip to ambient	$R_{thJA}$	75	
DIN humidity category, DIN 40 040		E	
IEC climatic category, DIN IEC 68-1		55 / 150 / 56	



NJ Semi-Conductors reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by NJ Semi-Conductors is believed to be both accurate and reliable at the time of going to press. However, NJ Semi-Conductors assumes no responsibility for any errors or omissions discovered in its use. NJ Semi-Conductors encourages customers to verify that datasheets are current before placing orders.

**BUZ 50 A**

**Electrical Characteristics, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Static Characteristics</b>					
Drain- source breakdown voltage $V_{GS} = 0\text{ V}$ , $I_D = 0.25\text{ mA}$ , $T_j = 25\text{ }^\circ\text{C}$	$V_{(BR)DSS}$	1000	-	-	V
Gate threshold voltage $V_{GS} = V_{DS}$ , $I_D = 1\text{ mA}$	$V_{GS(th)}$	2.1	3	4	
Zero gate voltage drain current $V_{DS} = 1000\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_j = 25\text{ }^\circ\text{C}$ $V_{DS} = 1000\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_j = 125\text{ }^\circ\text{C}$	$I_{DSS}$	-	20 100	250 1000	$\mu\text{A}$
Gate-source leakage current $V_{GS} = 20\text{ V}$ , $V_{DS} = 0\text{ V}$	$I_{GSS}$	-	10	100	nA
Drain-Source on-resistance $V_{GS} = 10\text{ V}$ , $I_D = 1.5\text{ A}$	$R_{DS(on)}$	-	4.5	5	$\Omega$

**BUZ 50 A**Electrical Characteristics, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Dynamic Characteristics</b>					
Transconductance $V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$ , $I_D = 1.5 \text{ A}$	$g_{fs}$	0.7	1.5	-	S
Input capacitance $V_{GS} = 0 \text{ V}$ , $V_{DS} = 25 \text{ V}$ , $f = 1 \text{ MHz}$	$C_{iss}$	-	1600	2100	pF
Output capacitance $V_{GS} = 0 \text{ V}$ , $V_{DS} = 25 \text{ V}$ , $f = 1 \text{ MHz}$	$C_{oss}$	-	70	120	
Reverse transfer capacitance $V_{GS} = 0 \text{ V}$ , $V_{DS} = 25 \text{ V}$ , $f = 1 \text{ MHz}$	$C_{rss}$	-	30	55	
Turn-on delay time $V_{DD} = 30 \text{ V}$ , $V_{GS} = 10 \text{ V}$ , $I_D = 2 \text{ A}$ $R_{GS} = 50 \Omega$	$t_{d(on)}$	-	30	45	ns
Rise time $V_{DD} = 30 \text{ V}$ , $V_{GS} = 10 \text{ V}$ , $I_D = 2 \text{ A}$ $R_{GS} = 50 \Omega$	$t_r$	-	40	60	
Turn-off delay time $V_{DD} = 30 \text{ V}$ , $V_{GS} = 10 \text{ V}$ , $I_D = 2 \text{ A}$ $R_{GS} = 50 \Omega$	$t_{d(off)}$	-	110	140	
Fall time $V_{DD} = 30 \text{ V}$ , $V_{GS} = 10 \text{ V}$ , $I_D = 2 \text{ A}$ $R_{GS} = 50 \Omega$	$t_f$	-	60	80	

**BUZ 50 A****Electrical Characteristics, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Reverse Diode</b>					
Inverse diode continuous forward current $T_C = 25^\circ\text{C}$	$I_S$	-	-	2.5	A
Inverse diode direct current, pulsed $T_C = 25^\circ\text{C}$	$I_{SM}$	-	-	10	
Inverse diode forward voltage $V_{GS} = 0\text{ V}, I_F = 6\text{ A}$	$V_{SD}$	-	1.05	1.3	V
Reverse recovery time $V_R = 100\text{ V}, I_F = I_S, di_F/dt = 100\text{ A}/\mu\text{s}$	$t_{rr}$	-	2	-	$\mu\text{s}$
Reverse recovery charge $V_R = 100\text{ V}, I_F = I_S, di_F/dt = 100\text{ A}/\mu\text{s}$	$Q_{rr}$	-	15	-	$\mu\text{C}$